



#18/E(NE)  
5/29/03  
PATENT  
Surles  
6/20/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 09/829,161

Filed: April 9, 2001

For: METALLIZATION STRUCTURES  
FOR SEMICONDUCTOR DEVICE  
INTERCONNECTS, METHODS FOR  
MAKING SAME, AND  
SEMICONDUCTOR DEVICES  
INCLUDING SAME

Confirmation No.: 8260

Examiner: H. Nguyen

Group Art Unit: 2812

Attorney Docket No.: 2269-3442.1US  
(96-0428.01/US)

Do not enter  
in 6-5-03

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

5/13/2003  
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Joseph A. Walkowski  
Name (Type/Print)

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AMENDMENT UNDER 37 C.F.R. §1.116

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P. O. Box 1450  
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Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Final Office Action mailed March 21, 2003, the three-month shortened statutory period for

response to which expires on June 21, 2003. This response is submitted on or before two months from the mailing date of the Final Office Action.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Remarks/Arguments** begin on page 14 of this paper.